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			Application Number	10/670,291	
			Confirmation Number	6427	
			Filing Date	September 26, 2003	
			First Named Inventor	Miwa KOZAWA et al.	
			Art Unit	1756	
			Examiner Name	Daborah Chacko-Davis	
Sheet	1	of	1	Attorney Docket Number	031181

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
		US			
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FOREIGN PATENT DOCUMENTS							
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NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.		Translation ⁴
/dcd/	1	TAKEO ISHIBASHI ET AL., Advanced Micro-Lithography Process with Chemical Shrink Technology, Japanese Journal of Applied Physics Vol. 40 (2001) pp. 419-425		
/dcd/	2	MAMORU TERA I ET AL., Below 70-nm Contact Hole Pattern with RELACS Process on ArF Resist, Advances in Resist Technology and Processing XX, Therodore H. Fedynyshyn, Editor, Proceedings of SPIE Vol. 5039 (2003)		
/dcd/	3	MAMORU TERA I ET AL., Newly Developed Resolution Enhancement Lithography Assisted by Chemical Shrink Process and Materials for Next-Generation Devices, Japanese Journal of Applied Physics Vol. 45, No. 6B (2006) pp. 5354-5358		

Examiner Signature	/Daborah Chacko-Davis/	Date Considered	10/30/2007
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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